

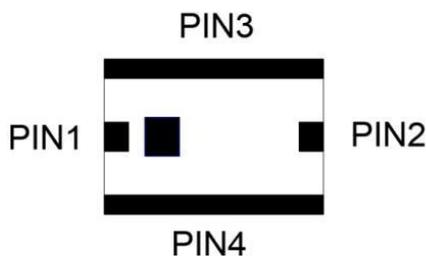
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

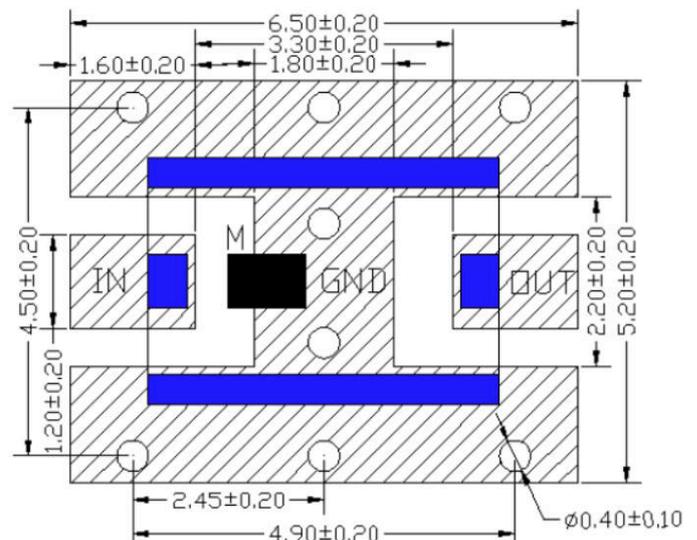
NO.	Parameter	Frequency (MHz)	SPEC	
			Min.	Max.
1	Insertion Loss (dB)	3750~4050		3.0
2	Ripple (dB)	3750~4050		0.5
3	Attenuation (dB)	DC~1650	48	
		2100~2700	35	
		3300	30	
		4200	4	
		4500	30	
		4800	30	
		5250~5550	50	
		5400	55	
		6750~7050	50	
	7500~8100	50		
4	VSWR	3750~4050		1.4
5	Phase linearity	3750~4050	±5°	
6	Multiple amplitude consistency(dB)	3750~4050		0.5
7	Phase Consistency	3750~4050	±5°	
8	In/Output Impedance (Ω)		50	

Construction

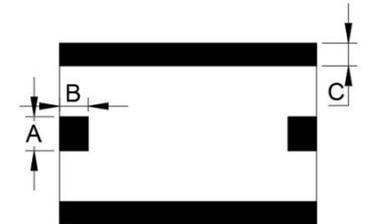


PIN	Connection
1	Input Port
2	Output Port
3	GND
4	GND

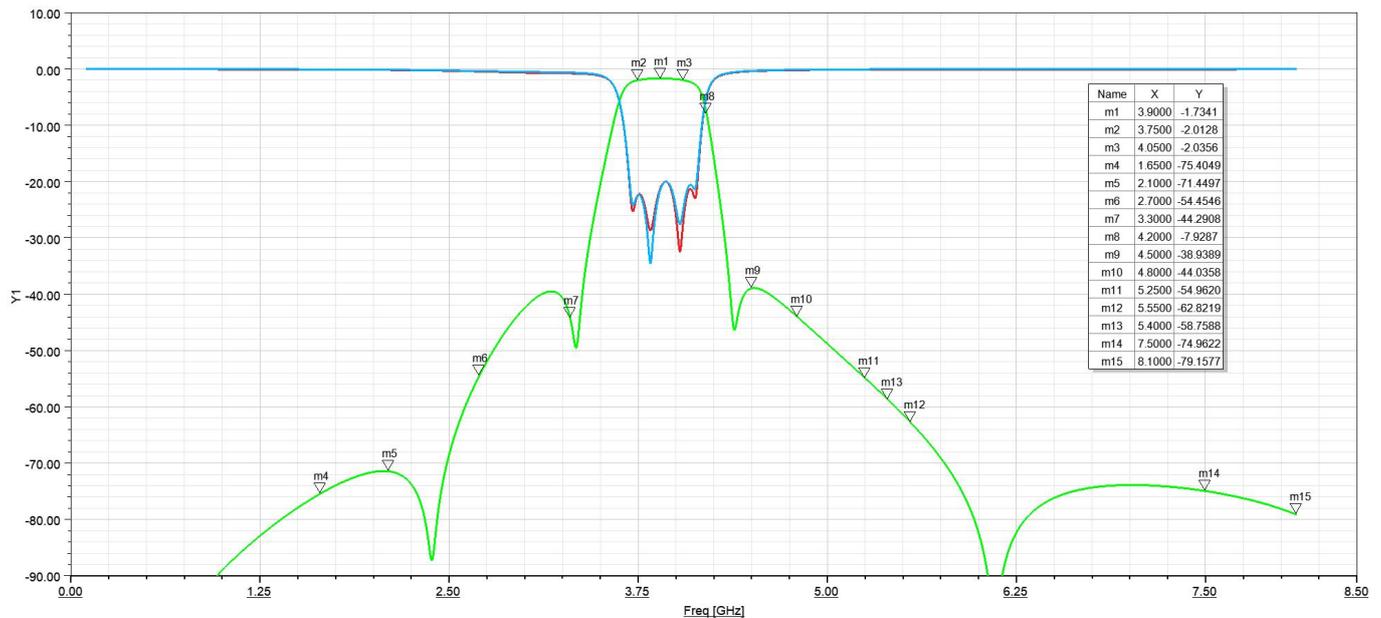
Mounting Considerations



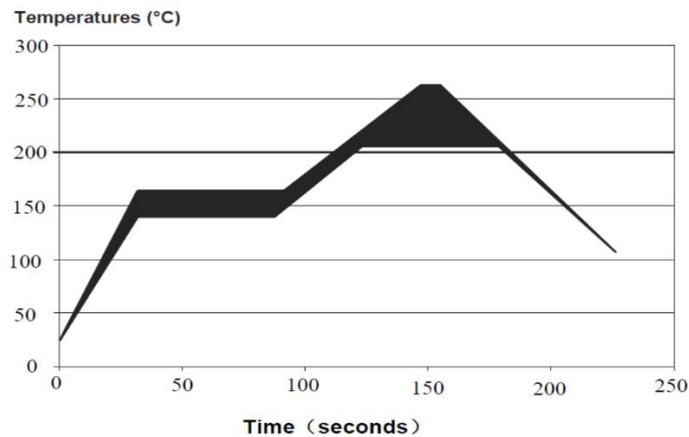
Dimensions

Figure	Symbol	Dimension (mm)
	L	4.50±0.20
	W	3.20±0.20
	T	1.50±0.20
	A	0.60±0.10
	B	0.50±0.10
	C	0.40±0.10

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.